
VE320 – Summer 2024

Introduction to Semiconductor Devices

Instructor: Yaping Dan (但亚平)
yaping.dan@sjtu.edu.cn

Chapter 0. Course Information and Preview



Outline

- **Course Information**
- Preview

Course Information

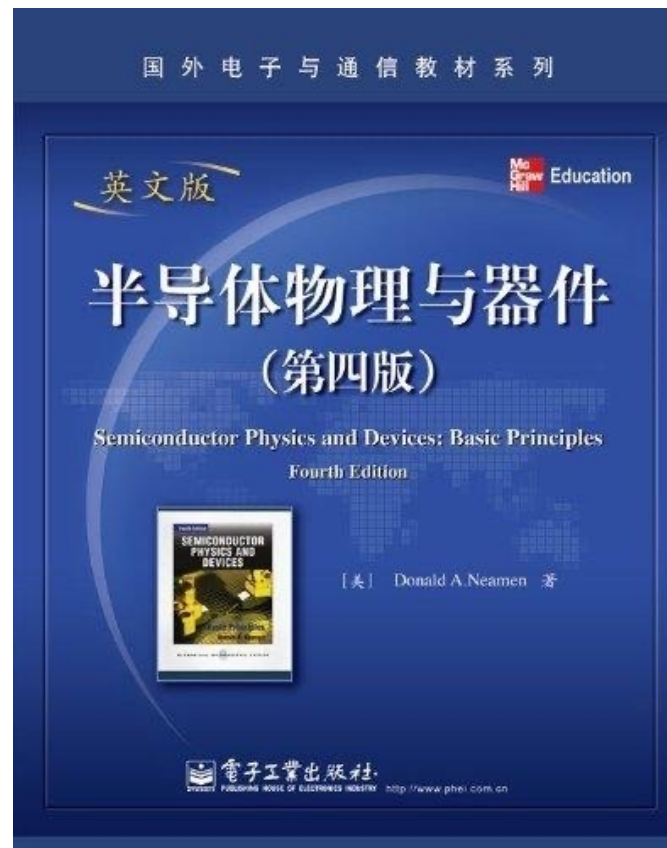
- Time: Tuesday 16:00-17:40
 Thursday 16:00-17:40
 Friday 16:00-17:40 (odd weeks)
- Instructor: Professor Dan, Yaping
 JI New Building Office 516
 Email: yaping.dan@sjtu.edu.cn
- Office Hour: 10am-12pm Tuesday, Thursday
- Teaching Assistants:
 - Zhou, Zhiyu : 020507zzy@sjtu.edu.cn
 - Chen, Zhuojia: chenzhuojia@sjtu.edu.cn
 - Zhou, Yuhao: zhouyuhao@sjtu.edu.cn

Reference textbook

Semiconductor Physics and Devices: Basic Principles 4th ed.

Donald A. Neamen

Publishing house of electronic industry



Grading Policy and Assignments

Grading Policy

- Activity & attendance in class and Piazza 7%
- Assignments 8%
- Midterm1(open book) 25%
- Midterm2(open book) 25%
- Final(open book) 35%

100%

- Overall score lower than 40 is F
- Bonus: one-on-one QA for those above 40 10%
- Curve to be centered at B+ or A- for those above 40.

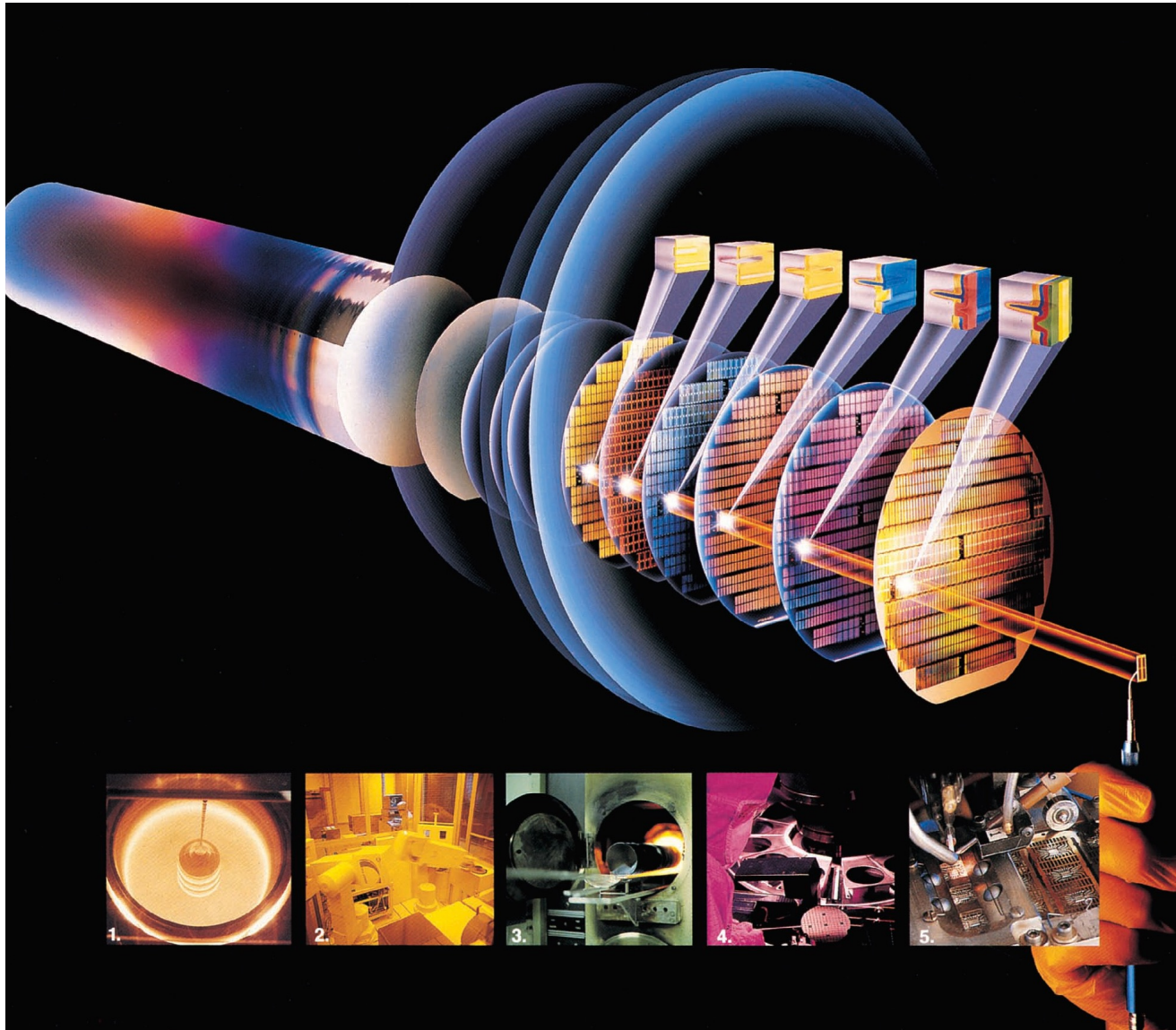
Assignments and Unethical Conducts

- Assigned weekly and due on the following week.
- Approximately seven problems each assignment.
- You are free to discuss homework with each other. But the work you submit must be your own.
- Any suspicious violation of the honor code will be reported to the honor council.
- Midterm and final exams are open-book.
- No internet access and no discussion during the exams.

Outline

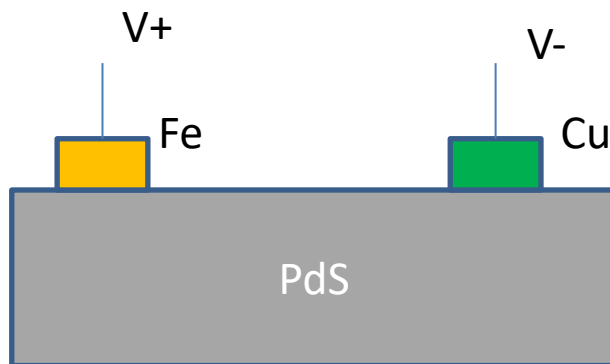
- Course Information
- **Preview**

Preview: Semiconductors and Integrated Circuits



Preview: Semiconductors and Integrated Circuits

The first semiconductor device:



Braun in 1874



Karl Ferdinand Braun

Shared the 1909 Nobel Prize in Physics with [Guglielmo Marconi](#) “for their contributions to the development of wireless telegraphy”

Preview: Semiconductors and Integrated Circuits

Quantum Mechanics → Semiconductor Physics

(1900 - 1950s)

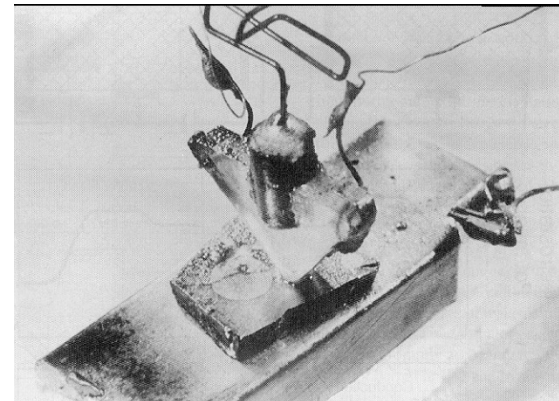
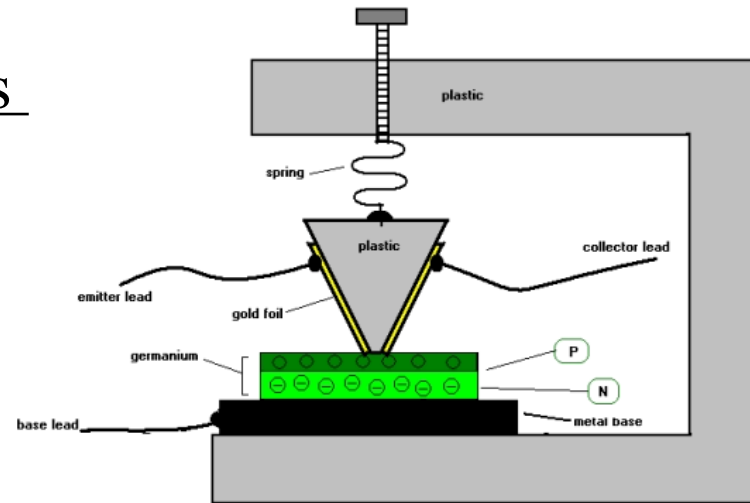
[Max Planck](#), [Niels Bohr](#), [Werner Heisenberg](#), [Louis de Broglie](#), [Arthur Compton](#), [Albert Einstein](#), [Erwin Schrödinger](#), [Max Born](#), [John von Neumann](#), [Paul Dirac](#), [Enrico Fermi](#), [Wolfgang Pauli](#), [Max von Laue](#), [Freeman Dyson](#), [David Hilbert](#), [Wilhelm Wien](#), [Satyendra Nath Bose](#), [Arnold Sommerfeld](#), and [others](#).

Preview: Semiconductors and Integrated Circuits

Explosion of integrated circuits



John Bardeen, William Shockley, and Walter Brattain at Bell Labs, 1948



First transistor Bell Labs, 1948
Based on Ge (锗)

Preview: Semiconductors and Integrated Circuits

Silicon Valley



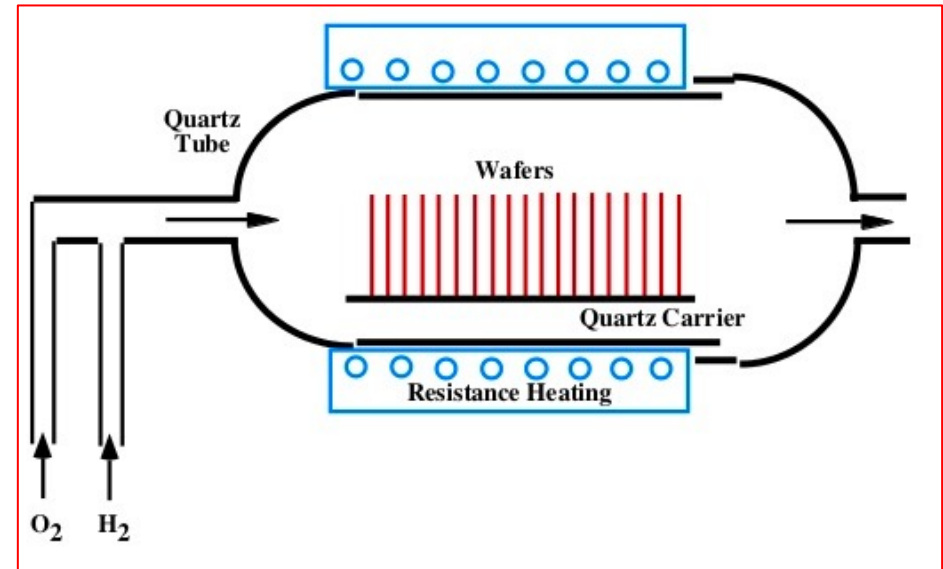
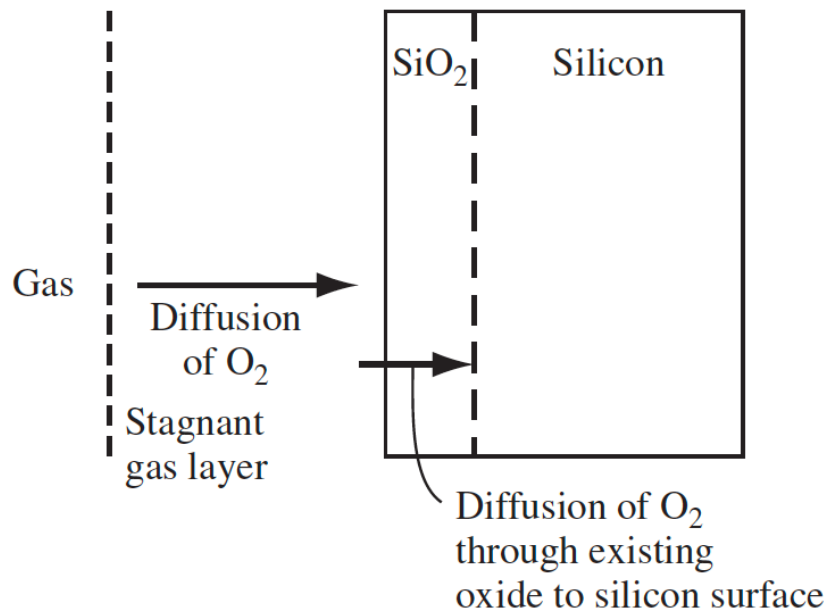
Bell Lab, New Jersey



Original site at California

Preview: Fabrication of Integrated Circuits

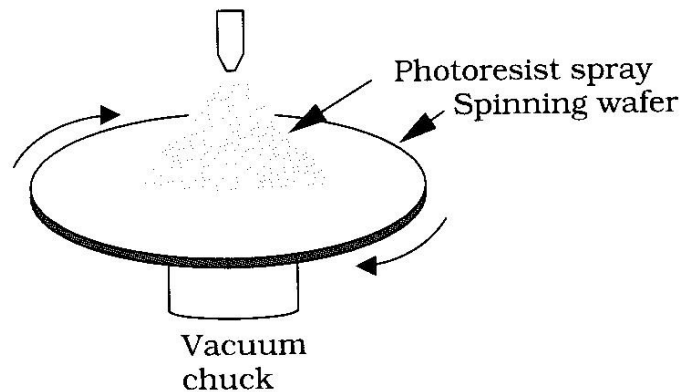
Thermal oxidation



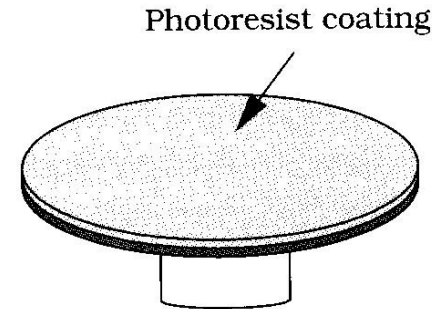
SiO₂: high quality electrical insulator

Preview: Fabrication of Integrated Circuits

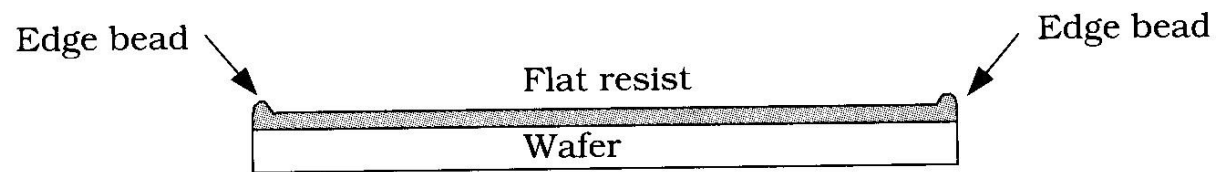
Photolithography



(a) Resist application



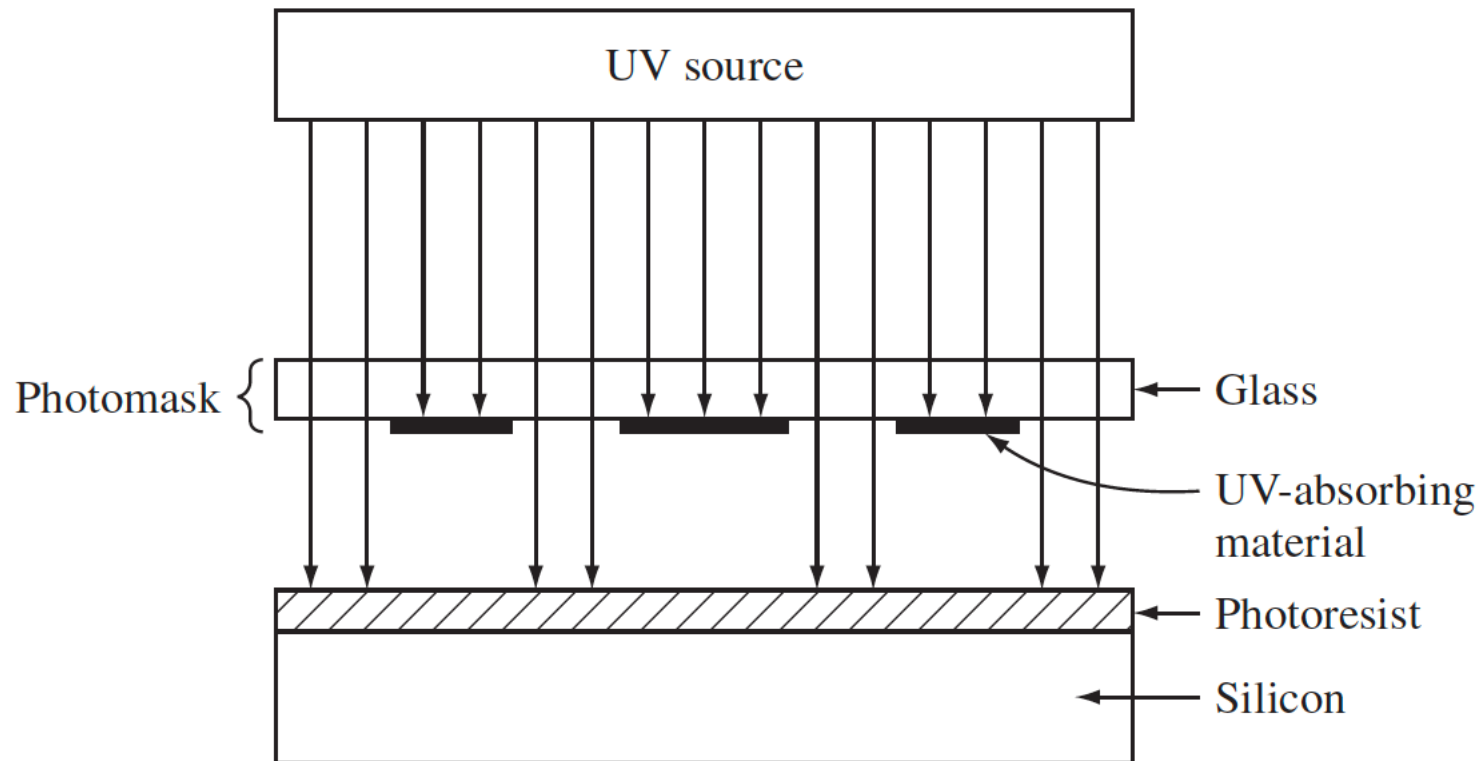
(b) Coated wafer



(c) Beading

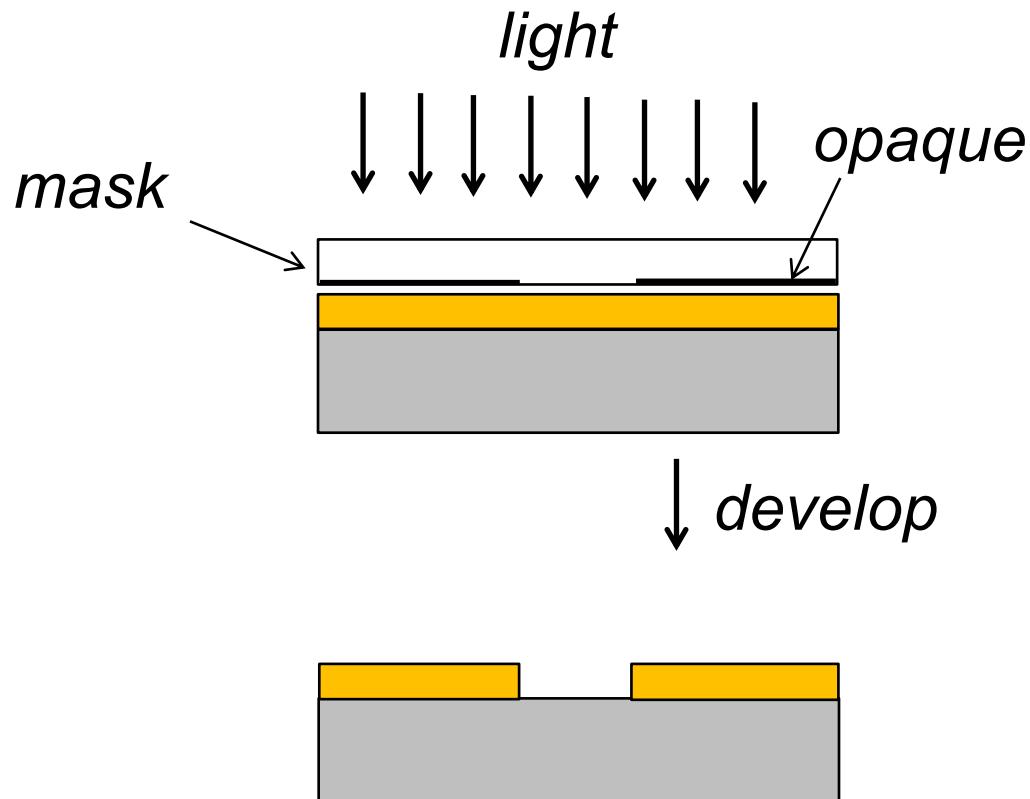
Preview: Fabrication of Integrated Circuits

Photolithography

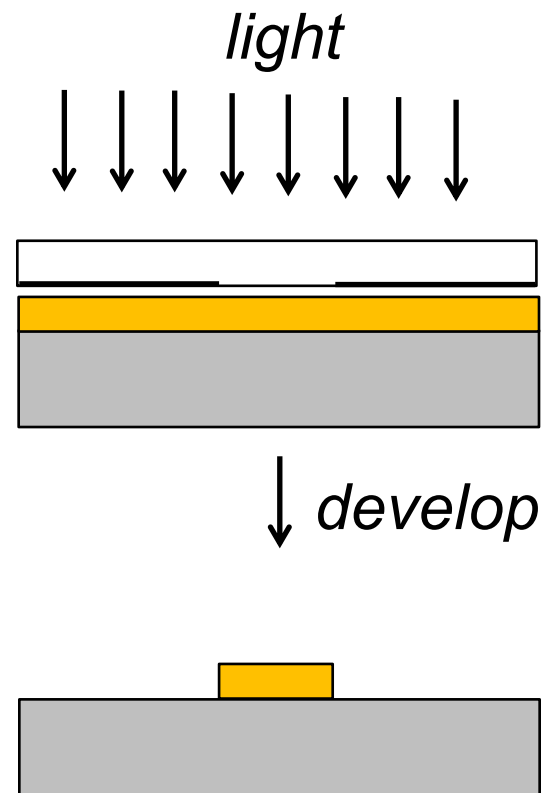


Preview: Fabrication of Integrated Circuits

Photolithography



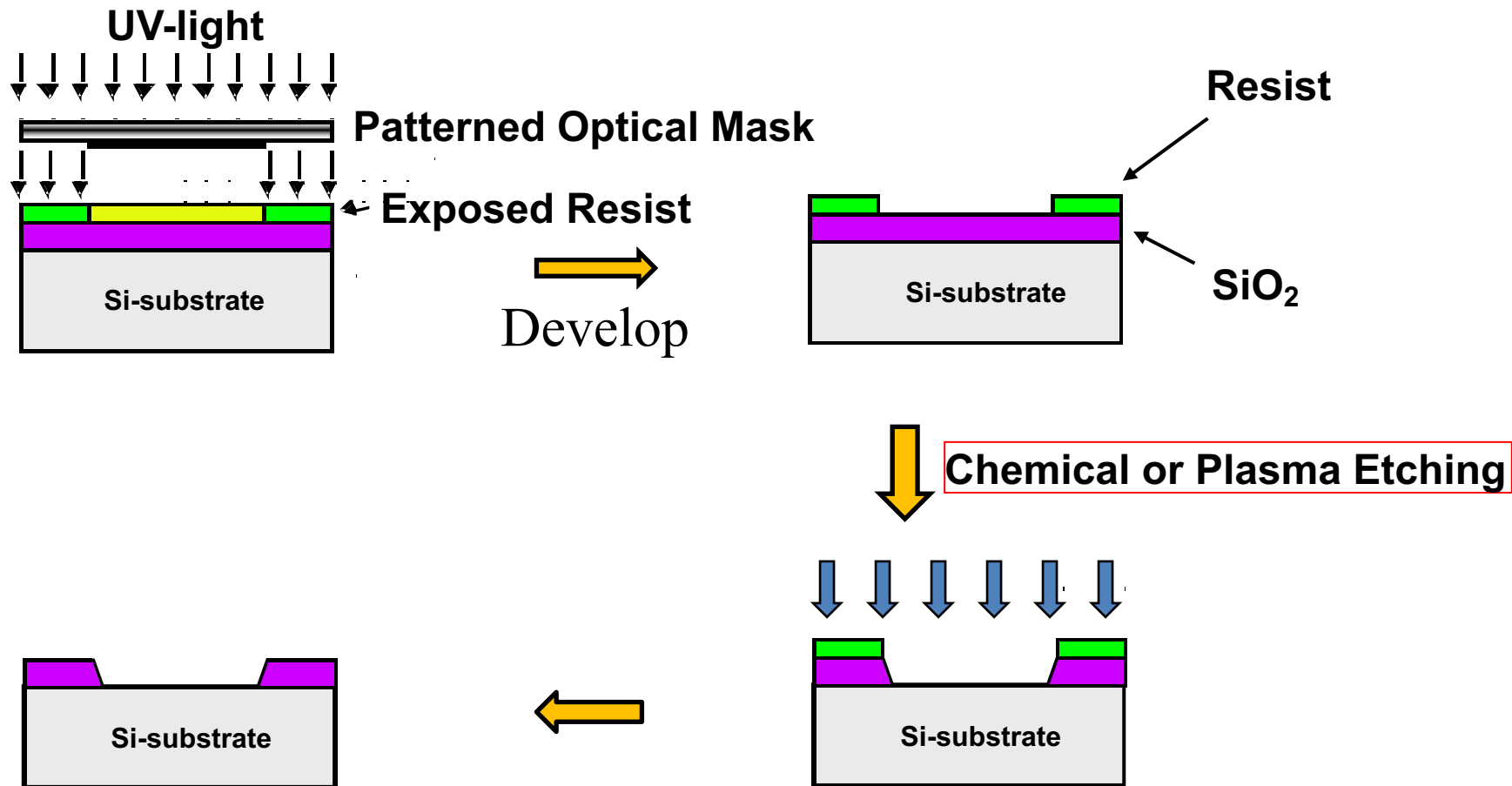
positive



negative

Preview: Fabrication of Integrated Circuits

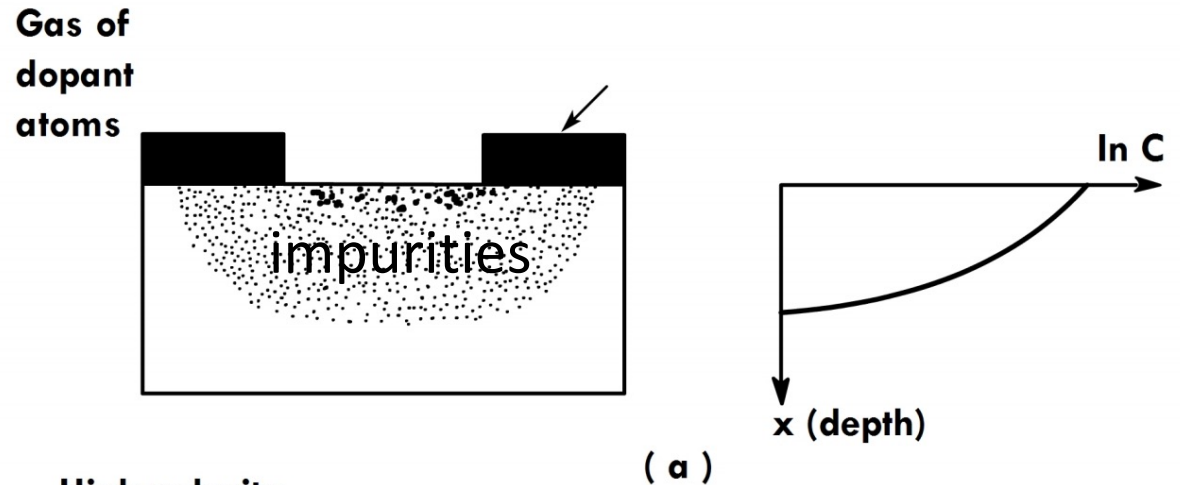
Etching



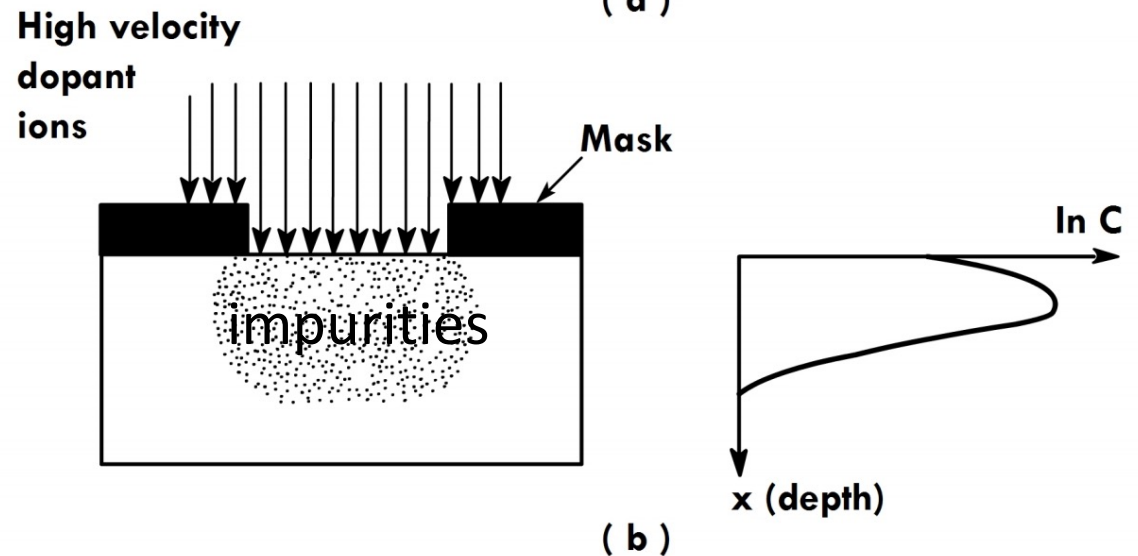
Preview: Fabrication of Integrated Circuits

Doping

Thermal diffusion

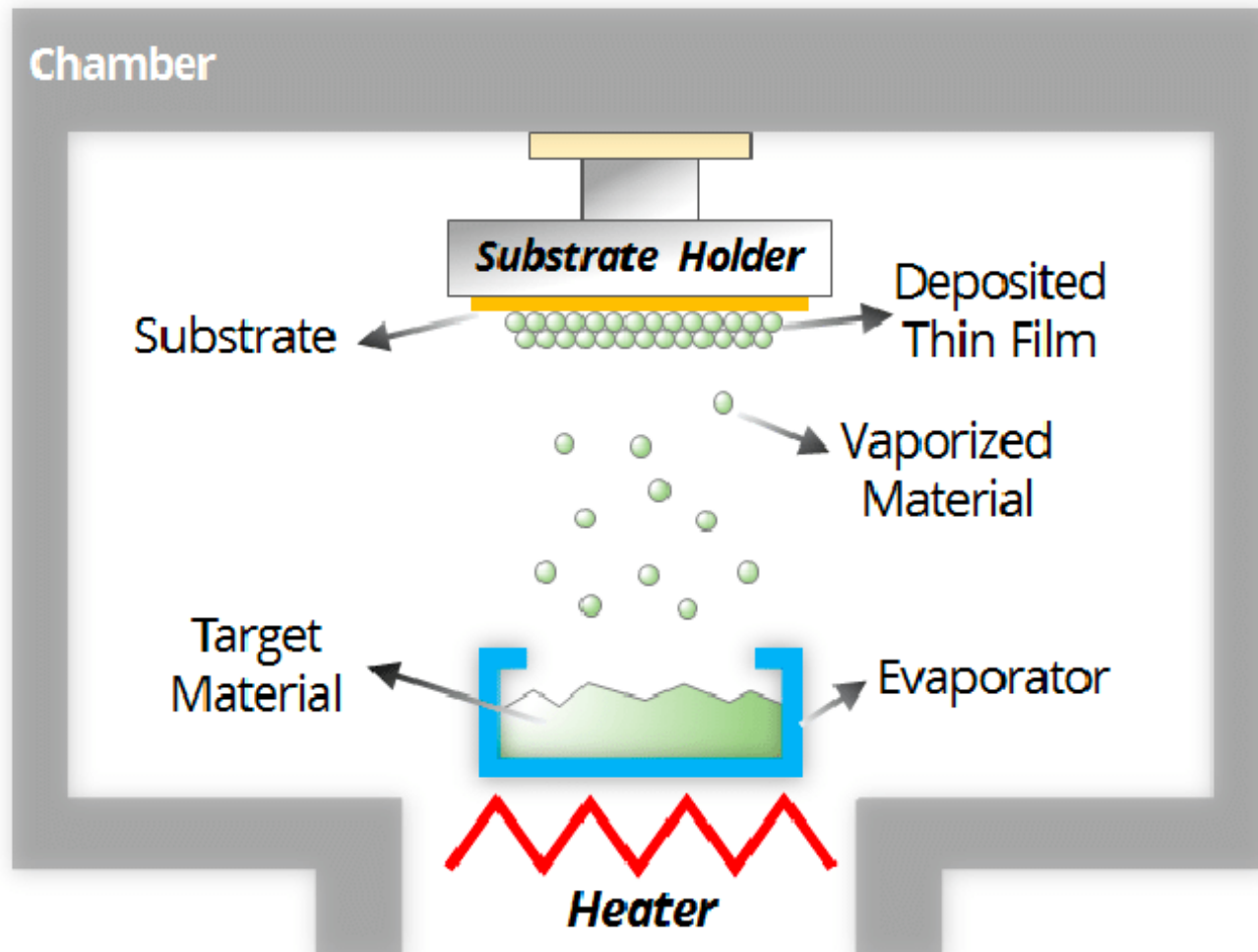


Ion implantation



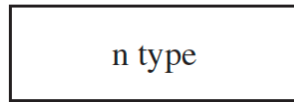
Preview: Fabrication of Integrated Circuits

Metallization (metal deposition)

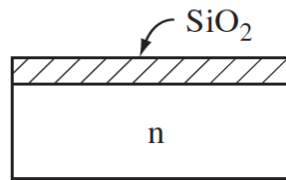


Preview: Fabrication of Integrated Circuits

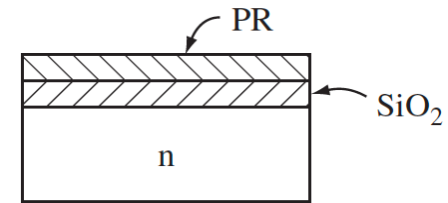
Simple Fabrication Process



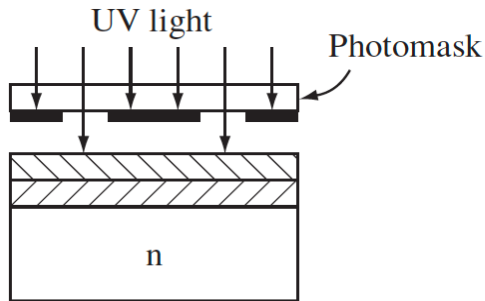
1. Start with
n-type substrate



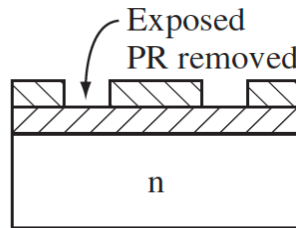
2. Oxidize surface



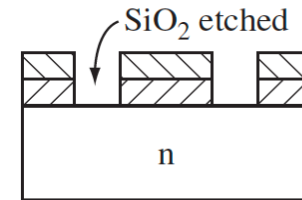
3. Apply photoresist
over SiO_2



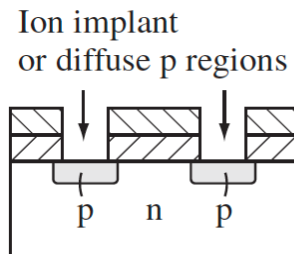
3. Expose photoresist
through photomask



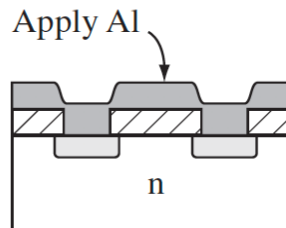
4. Remove exposed
photoresist



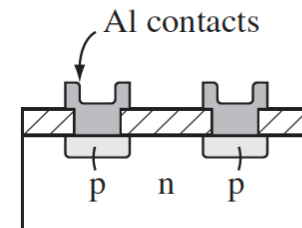
5. Etch exposed SiO_2



6. Ion implant or
diffuse boron
into silicon



7. Remove PR and
sputter Al on
surface



8. Apply PR, photomask,
and etch to form Al
contacts over p regions

Preview: Fabrication of Integrated Circuits

